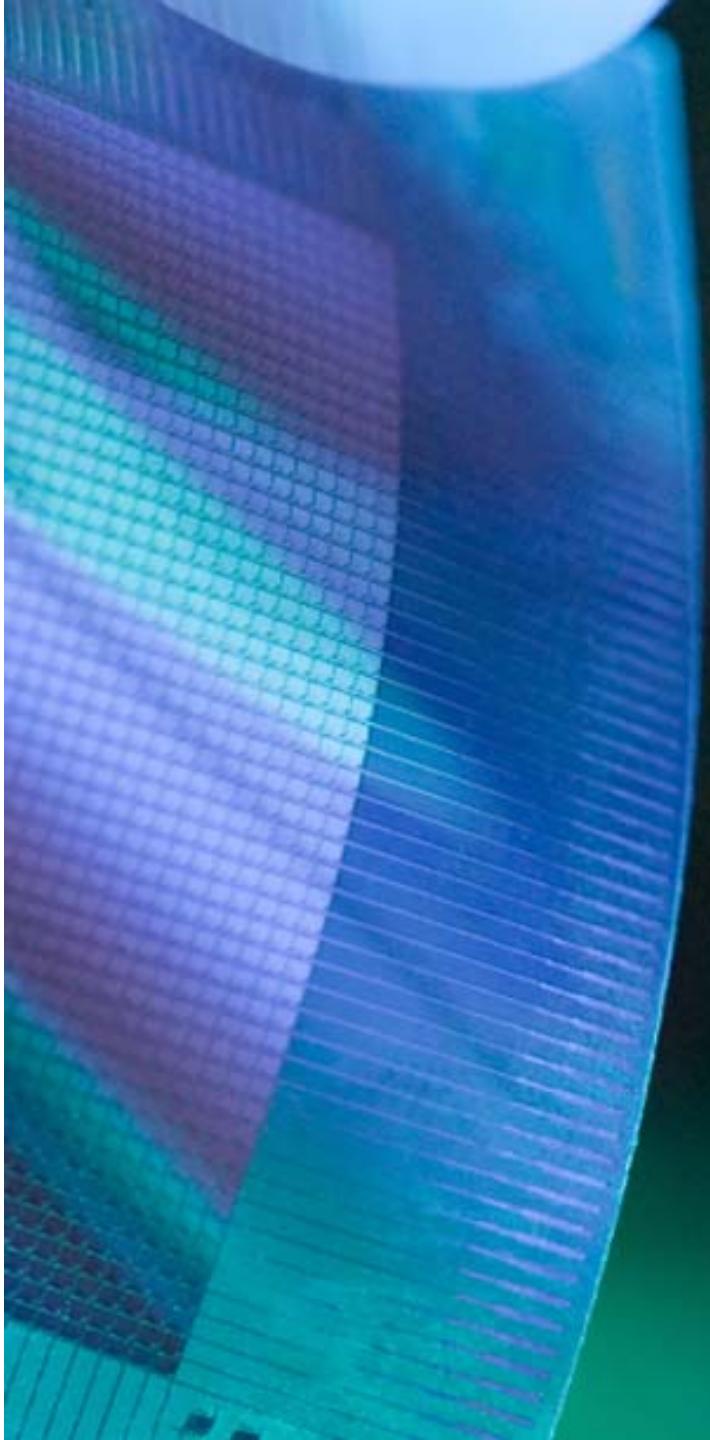


Challenges and opportunities for the flexible electronics industry

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about PARC



Palo Alto Research Center
– incorporated in 2002 (formerly Xerox PARC)

◆ 4 Divisions

- Computer Science
- Intelligent Systems
- Hardware Systems
- Electronic Materials & Devices

**Large Area Electronics,
MEMS, Optoelectronics,
Printing Systems,
Biomedical Systems,
Clean Technology, ...**

about PARC



Palo Alto Research Center
– incorporated in 2002 (formerly Xerox PARC)

◆ Research as a business

- Research with client companies and the Government
- Partnerships with new ventures
- New business creation
- Licensing and technology transfer

The Vision for Flexible Electronics

- ◆ **There will be new applications that utilize flexibility**
- ◆ **And new applications that benefit from flexibility**
 - Lighter, more robust,.....
 - Lowered cost of manufacturing
 - Custom devices and systems
- ◆ **A destabilizing technology will be created**
 - There are likely to be new winners
 - ▶ Will they be in Asia, Europe or USA?

Applications that need flexibility

◆ **Displays**

- Placed on curved surfaces, wearable
- Roll-able
- Robust

◆ **Photovoltaics**

- Placed on curved surfaces
- Aesthetics as well as function

◆ **Digital X-ray imagers**

- Conformal – surrounding the object
- Robust

◆ **Medical devices**

- Electronic patch
- Implantables

◆ **Systems on a foil**

- Wearable devices
- Designed for people, not imposed on them

Benefits to industry from flexible substrates

◆ Roll-roll manufacturing

- Exists in many areas: newspapers, packages.....
- Low cost at high volume

◆ Thin, light substrates

- Ultra-light systems
- Stackable

◆ Robustness

- No brittle devices

◆ Examples

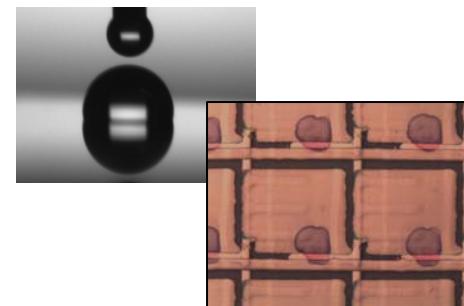
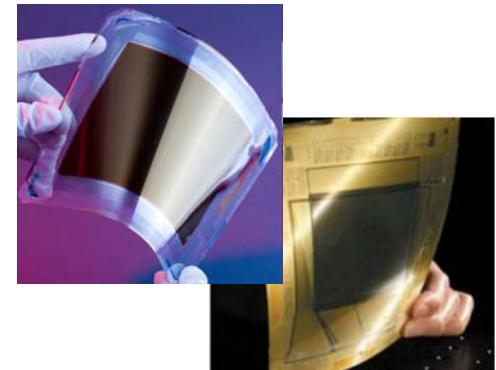
- RFID
- Photovoltaics
- Smart labels
- Lighting
- Smart phones
- Tablets.....

Our perspective:

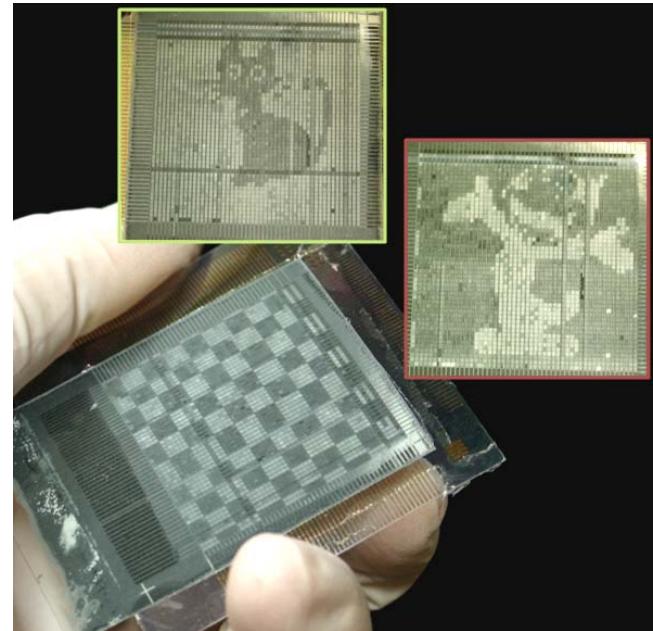
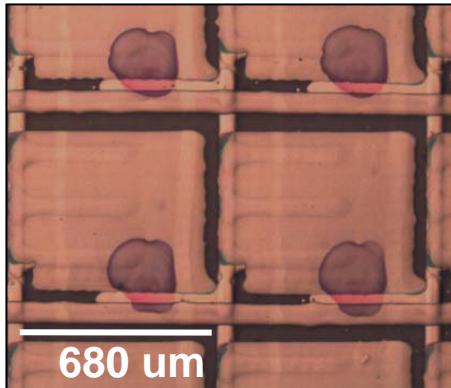
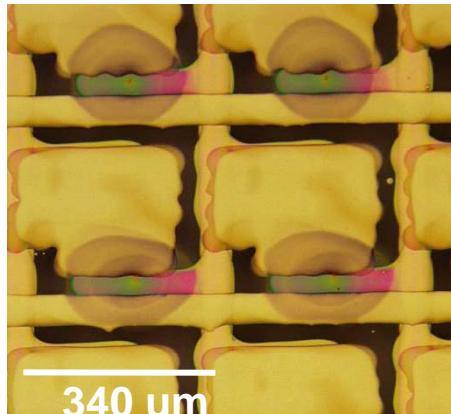
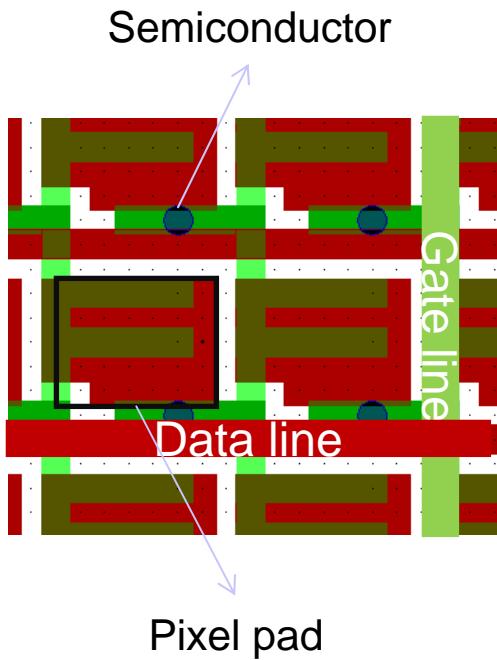
- ◆ **Flexible Electronics is an exciting opportunity**
 - New technology capabilities
 - New business opportunities
- ◆ **And – it is happening**
 - Particularly in Europe
- ◆ **Applications will drive the technology**
 - People want solutions – not technology
 - And they want convergence of functions
- ◆ **Challenges**
 - Commercial: How can we launch the industry?
 - Government: Where is the best leverage?

PARC's approach

- ◆ **Make “standard” technologies flexible**
 - Amorphous and poly-crystalline Si
- ◆ **Exploit printing technology**
 - Inkjet
 - Gravure
- ◆ **Develop organic electronics**
- ◆ **Demonstrate with applications**
 - Displays
 - Sensors
 - Systems
- ◆ **Develop hybrid approaches**



Example 1: All-additive printed arrays



PARC has demonstrated all-printed TFT backplanes for displays

Why this is important

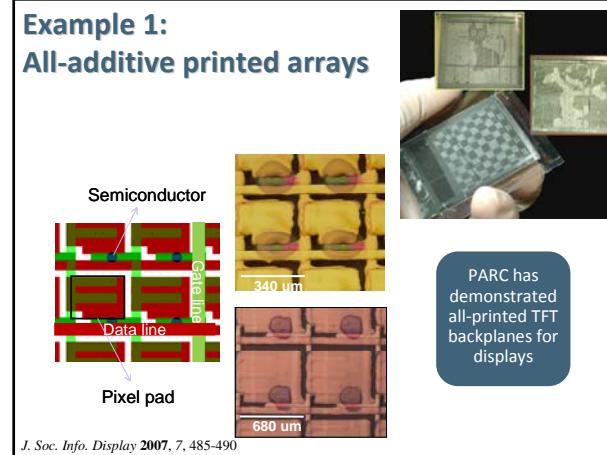
◆ Fewer steps

- Printed:
 - ▶ 4 layers = 4 steps
- Traditional:
 - ▶ 4 layers = 16-20 steps

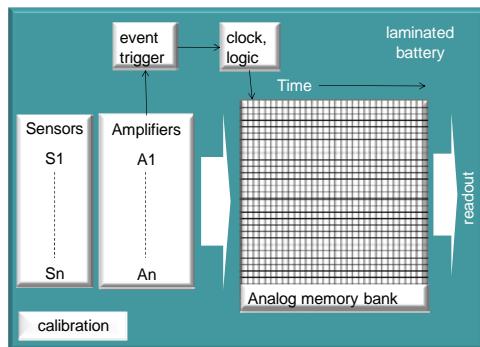
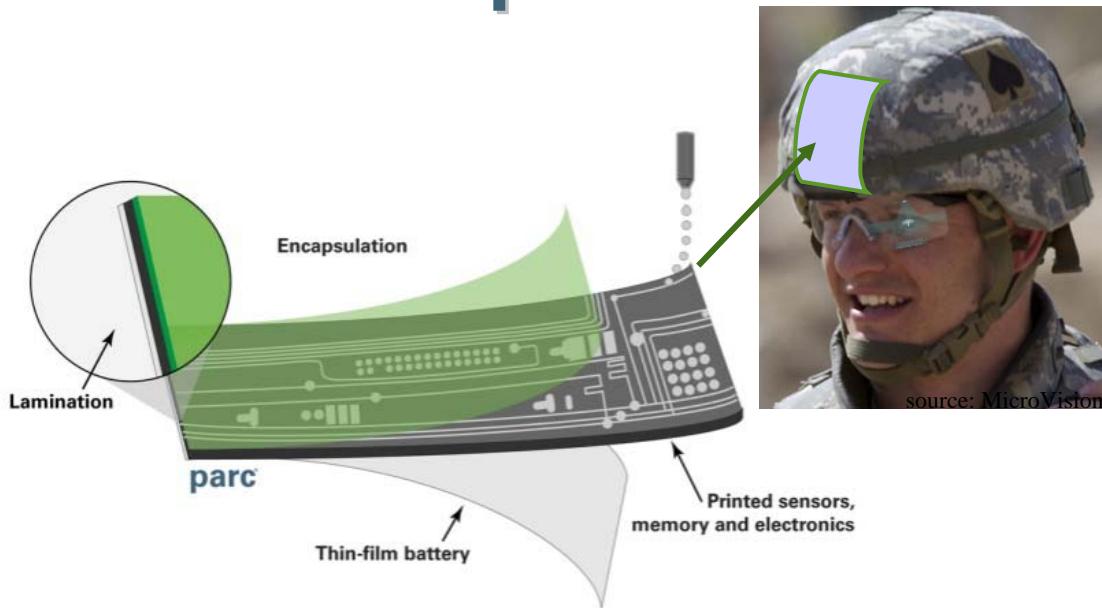
◆ Scalable to simpler applications

- custom applications
- Smart labels etc.

Example 1: All-additive printed arrays



Example 2: Printed Sensor Tape



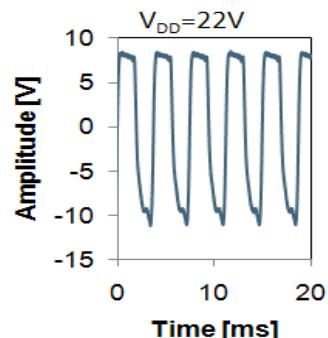
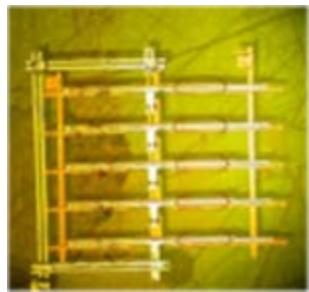
- Monitor pressure, acceleration, sound, light
- Signals recognized, processed, sent to memory
- Non-volatile memory holds data for one week
- Off-board readout system

Monitoring environment to prevent traumatic brain injury. **parc**
(DARPA)

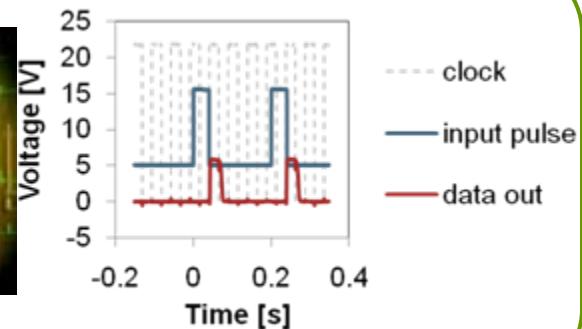
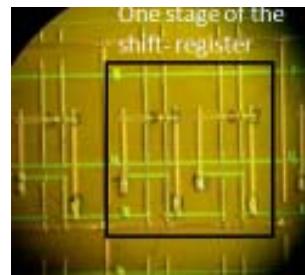
A Xerox Company

Sensor Tape: Printed Electronics

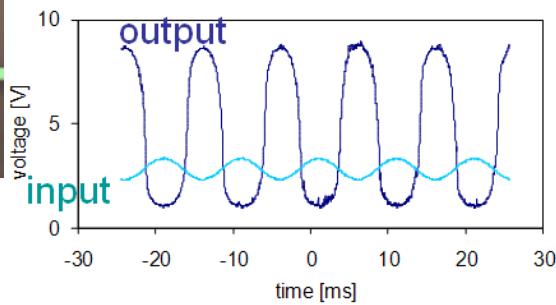
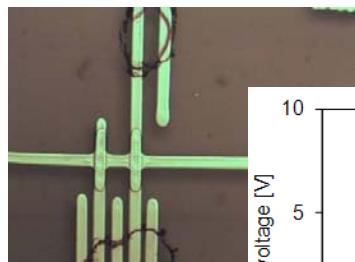
Ring oscillator



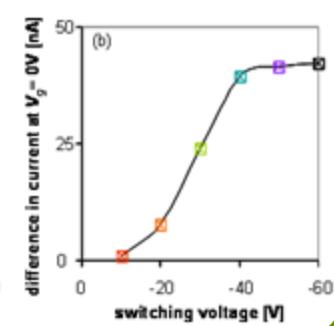
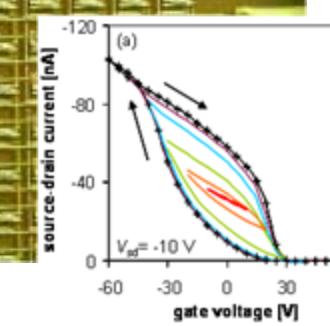
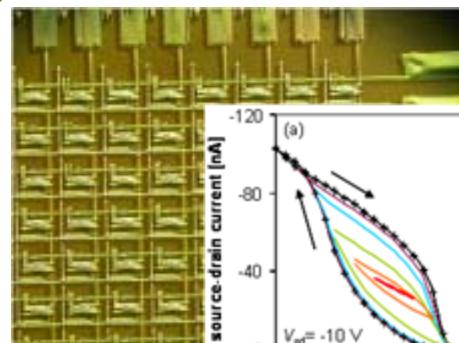
Shift Register



Amplifier

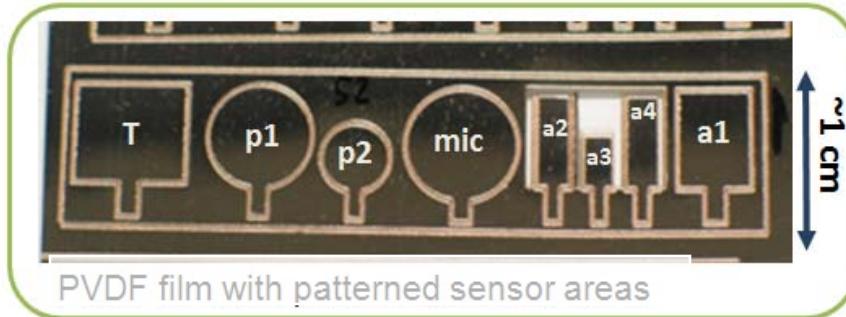
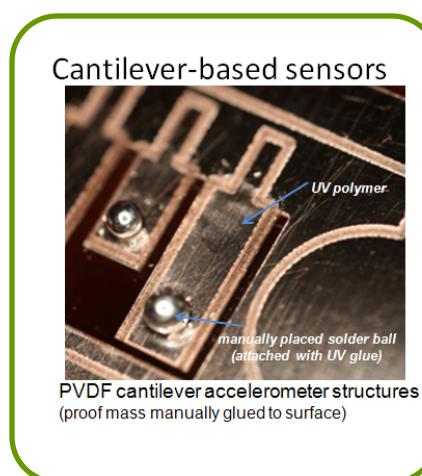
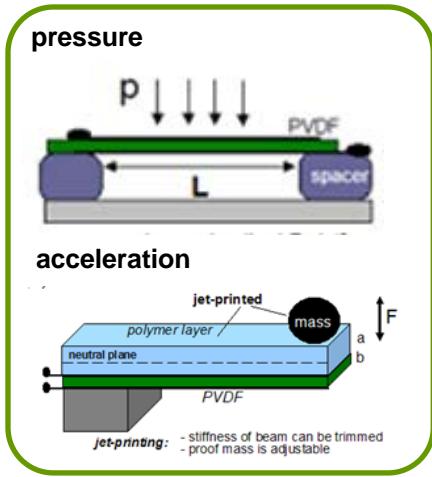


Memory



Sensors

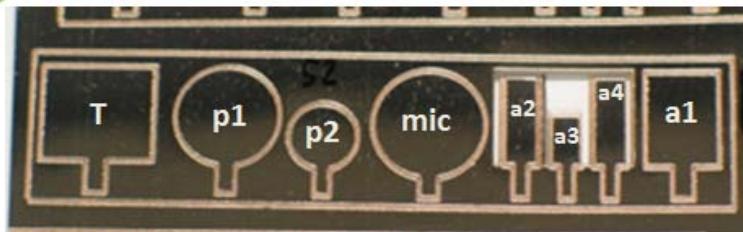
◆ Piezoelectric sensing



Laminated PVDF foil or PVDF-TrFE solution

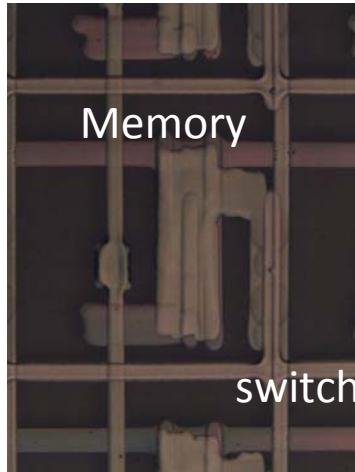
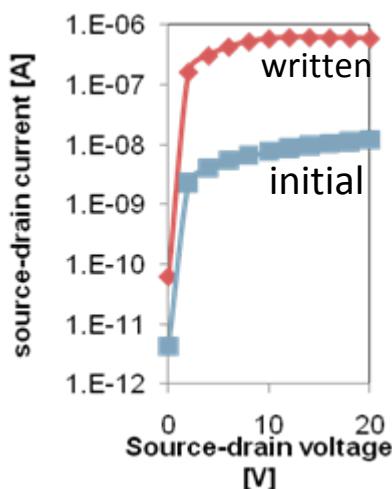
Sensor Tape: Next step: integration

MEMS sensors

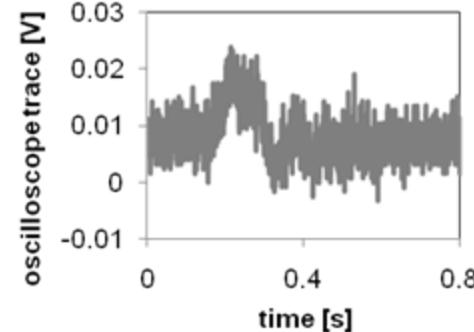
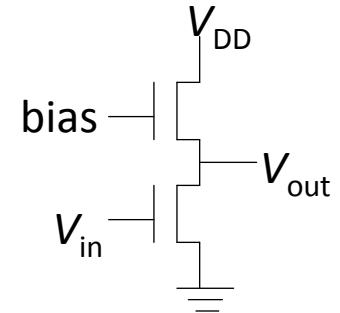


PVDF film with patterned sensor areas

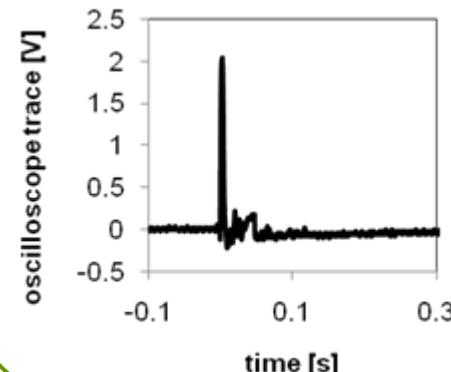
Printed memory cells



Printed organic amplifiers



Pressure signal without amplifier



Pressure signal after amplifier

What we have learned

- ◆ **Flexible sensor systems will be important**
- ◆ **Hybrid devices are very promising**
 - Silicon + organics
 - Printed + traditional manufacturing
- ◆ **Integration into a system can be done**
 - but is challenging
- ◆ **Taking this to the next level is difficult**
 - Applications need volume
 - Volume needs applications
 - Does the industry wait for a company with enough money and demand to drive the development of a particular device
AND the industry itself?

Example 2:
Printed Sensor Tape

The diagram illustrates a printed sensor tape system. It shows a cross-section of the tape with layers labeled: 'Polymer', 'Lamination', 'Polymer', and 'Polymer'. A green circle highlights the 'Polymer' layer. A photograph of a soldier wearing a helmet and goggles is shown, with a green box indicating the location of the sensor tape on his forehead. Labels point to 'Printed sensors, memory and electronics' and 'Thin-film battery'. Below the diagram, a block diagram shows the system architecture: Sensors (S1-S4) feed into an Amplifier (A1-A4), which then connects to a Data Processor. The Data Processor is connected to a Non-volatile memory (1 week) and an Off-board readout system. A legend provides the following details:

- Monitor pressure, acceleration, sound, light
- Signals recognized, processed, sent to memory
- Non-volatile memory holds data for one week
- Off-board readout system

Monitoring environment to prevent traumatic brain injury.
(DARPA)

PARC's view

- ◆ **The flexible electronics industry has a huge future**
- ◆ **We are active across the industry and work with a wide range of participants**
- ◆ **With our clients and partners, we invent, develop and demonstrate**
 - Processes
 - Prototypes
 - Applications
- ◆ **We are investing in**
 - Components
 - Partnerships for manufacturing

What more is needed?

◆ Focus on development of applications

- There is currently some funding for processes and capabilities
 - ▶ This should be enhanced
- We need to put this together with applications
 - ▶ The big missing piece in the US

◆ This could kick-start the industry

.... the relatively low prevalence of actual manufacturing and advanced systems research and development in the United States has led to an incomplete hybrid flexible electronics R&D scenario for this country..... [NSF/ONR Report: www.wtec.org/flex/]

Thank you

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